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Information Disclosure
Statement By Applicant

Atty Docket No. NOVL085/NVLS-2875 Application No.: 10/785,235

Applicant:

Wang et al. Filing Date

Group

(Use Several Sheets if Necessary)

February 23, 2004

2812 2823

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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.